particle diameter of the inorganic filler mixed with the insulating resin of the anisotropic conductive layer is not smaller than 3 μm.

15. An electronic component mounting method as claimed in any one of claims 1 through 3 and 14, wherein the inorganic filler mixed with the insulating resin of the anisotropic conductive layer is comprised of at least two types of inorganic fillers (6f-1, 6f-2) that have a plurality of different mean particle diameters, and a mean particle diameter of one inorganic filler (6f-1) out of at least two types of inorganic fillers is not less than two times different from a mean particle diameter of the other inorganic filler (6f-2) out of at least two types of inorganic fillers.

16. An electronic component mounting method as claimed in any one of claims 1 through 3, 14 and 15, wherein the anisotropic conductive layer has a portion brought in contact with either the electronic component or the board, the portion having a smaller amount of inorganic filler than that of the other portion.

17. An electronic component mounting method as claimed in claim 15, wherein the anisotropic conductive layer has a portion brought in contact with both the electronic component and the board, the portion having a smaller amount of inorganic filler than that of the other

portion.

18. An electronic component unit, wherein an electrode (2) of an electronic component (1) is electrically connected to an electrode (5) of a circuit board (4) with a bump (3, 103) formed on the electrode (2) of the electronic component (1) and bonded to the electrode (5) of the circuit board (4) in a state in which the bump is crushed with interposition of an anisotropic conductive layer (10), in which an insulating resin (6m) is mixed with an inorganic filler (6f) and hardened, and

the anisotropic conductive layer (10) has a portion brought in contact with either the electronic component or the board, the portion having a smaller amount of inorganic filler than that of the other portion.

19. An electronic component unit, wherein an electrode (2) of an electronic component (1) is electrically connected to an electrode (5) of a circuit board (4) with a bump (3, 103) formed on the electrode (2) of the electronic component (1) and bonded to the electrode (5) of the circuit board (4) in a state in which the bump is crushed with interposition of an anisotropic conductive layer (10), in which an insulating resin (6m) is mixed with an inorganic filler (6f) and hardened, and

the anisotropic conductive layer (10) comprises: a first resin layer (6x), which is positioned in a portion

brought in contact with either the electronic component or the board and in which an insulating resin identical to the insulating resin is mixed with the inorganic filler; and a second resin layer (6y), which is in contact with the first resin layer and is made of an insulating resin whose amount of the inorganic filler is less than that of the first resin layer.

20. An electronic component mounting method as claimed in any one of claims 1 through 9, and 14 through 17, wherein the bump is a bump formed by plating or printing.

21. An electronic component unit as claimed in any one of claims 18 through 19, wherein the bump is a bump formed by plating or printing.

22. An electronic component mounting method as claimed in any one of claims 1 through 9, 14 through 17 and 20, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler with a conductive particle (10a) that has a mean diameter greater than a mean particle diameter of the inorganic filler.

23. An electronic component mounting apparatus as claimed in any one of claims 10 through 12, wherein the anisotropic conductive layer is provided by mixing the solid insulating resin mixed with the inorganic filler (6f) with a conductive particle (10a) that has a mean diameter